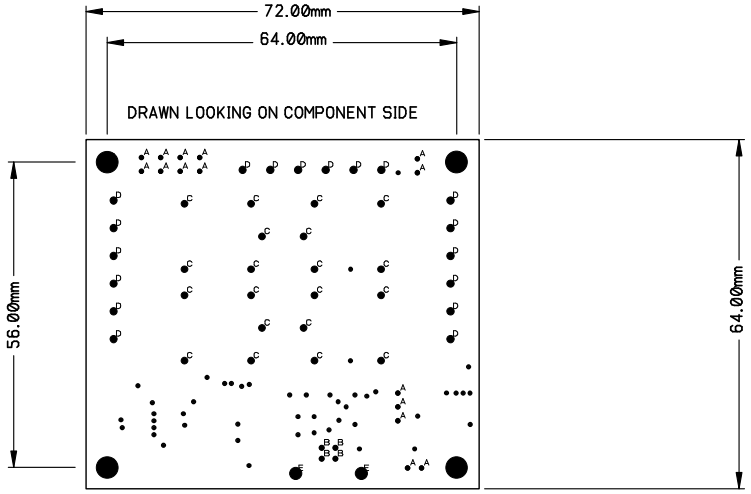

Countersink M3 from the rear for the 4 corner holes.
M3 CSK screw to be mounted through the PCB from the rear and basically be flush with the rear of the PCB when screwed into a topside mounted pillar.

MATERIAL:
EPOXIDE RESIN BONDED GLASS FABRIC
FR4 TO BS4584 PT.4
2 LAYER 2oz COPPER 1.6mm THICK

FINISH
HOT AIR LEVEL FINISH
SOLDER RESIST PROBIMER 52 (GREEN) BOTH SIDES
SILKSCREEN COMPT SIDE - WHITE NOTATION INK

ALL HOLES TO BE PLATED THROUGH UNLESS OTHERWISE STATED
HOLES IDENTIFIED THUS:* ARE NON PTH
ALL HOLE SIZES APPLY AFTER PLATING THROUGH
PROFILE BOARD TO DIMENSIONS GIVEN, EDGES TO BE FREE OF COPPER AFTER PLATING

DRILL DATA

UNREF HOLES 0.5mm(0.020") DIA 47 OFF (UNREF VIAS)
A HOLES 0.9mm(0.036") DIA 15 OFF
B HOLES 1.0mm(0.040") DIA 4 OFF
C HOLES 1.3mm(0.052") DIA 20 OFF
D HOLES 1.6mm(0.063") DIA 18 OFF
E HOLES 2.3mm(0.090") DIA 2 OFF
F HOLES 4.0mm(0.158") DIA 4 OFF

MANUFACTURING FILES

100_DA_2008_001-A-L1.SPL LAYER1 (COMPONENT SIDE)
100_DA_2008_001-A-L2.SPL LAYER2 (SOLDER SIDE)
100_DA_2008_001-A-SSL1.SPL SILKSCREEN (COMPT SIDE)
100_DA_2008_001-A-SSL2.SPL SILKSCREEN (SOLDER SIDE)
100_DA_2008_001-A-SRL1.SPL SOLDERMASK (COMPT SIDE)
100_DA_2008_001-A-SRL2.SPL SOLDERMASK (SOLDER SIDE)
100_DA_2008_001-A-NCD.SPL NC DRILL FILE
100_DA_2008_001-A-NCD.REP DRILL SIZE REP
100_DA_2008_001-A-DWG.SPL DRILL DWG (THIS DWG)

100_DA_2008_001-A-SPL1.SPL SOLDERPASTE (COMPT SIDE)
100_DA_2008_001-A-SPL2.SPL SOLDERPASTE (SOLDER SIDE)

ISSUE	ECO	DATE	ISSUE	ECO	DATE
			A		08-04-08

GOLDCHIP COMPUTERS Ltd.
BROOK LANE, CORFE MULLEN,
WIMBORNE, DORSET. BH21 3RD

TITLE: DRILL & PROFILE DETAILS
USB4PRMx CARD

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TOLERANCES
GENERAL +/-0.3
HOLE DIA +0.1 -0
AFTER PLATING +0.1 -0
UNLESS STATED OTHERWISE

DRAWN	CHECKED	APPROVED	USED ON
CADLAY			
08-04-08			

A3

CAD GENERATED DRAWING | SHT OF SHTS

DRG. NO. 100/DA/2008/001